

# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

| Characteristic  | Symbol  | Value | Unit |
|---|---|-------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage              | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>RM</sub> | 200   | V    |
| Average Rectified Output Current (See Figure 1)   | lo  | 1.0   | А    |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine-Wave Superimposed on Rated Load | I <sub>FSM</sub>  | 40    | А    |

### **Thermal Characteristics**

| Characteristic  | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Maximum Thermal Resistance Junction to Ambient (Note 5) | R <sub>0JA</sub>                  | 217         | °C/W |
| Maximum Thermal Resistance Junction to Ambient (Note 6) | R <sub>θJA</sub>                  | 138         | °C/W |
| Operating and Storage Temperature Range                 | T <sub>J</sub> , T <sub>STG</sub> | -65 to +175 | °C   |

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic           | Symbol          | Min | Тур  | Max  | Unit | Test Condition  |
|--------------------------|-----------------|-----|------|------|------|---|
| Forward Voltage          | \/_             | -   | 0.75 | 0.82 | V    | I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C   |
|                          | VF              | -   | 0.60 | 0.68 |      | I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25⁰C<br>I <sub>F</sub> = 1.0A, T <sub>J</sub> = +125⁰C |
| Reverse Current (Note 7) | I <sub>R</sub>  | -   | -    | 50   | μA   | V <sub>R</sub> = 200V, T <sub>J</sub> = +25°C   |
| Reverse Recovery Time    | t <sub>RR</sub> | -   | -    | 25   |      | $I_F = 0.5A, I_R = 1A,$   |
|                          |                 |     |      |      |      | I <sub>RR</sub> = 0.25A   |

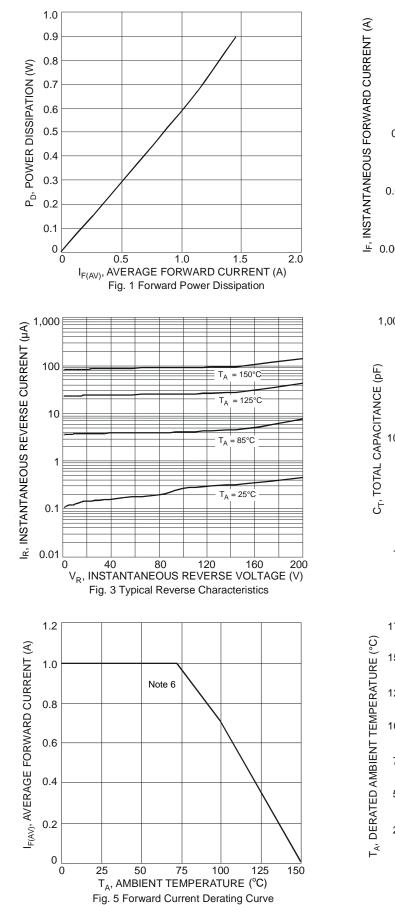
Notes: 5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.

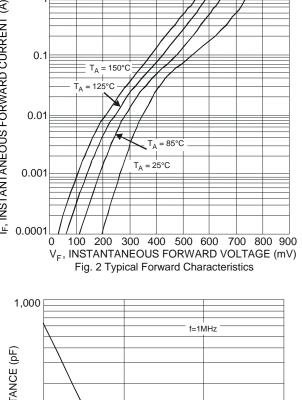
6. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.

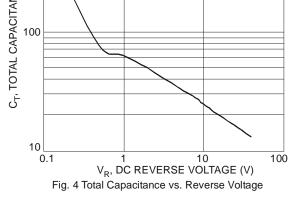
7. Short duration pulse test used to minimize self-heating effect.

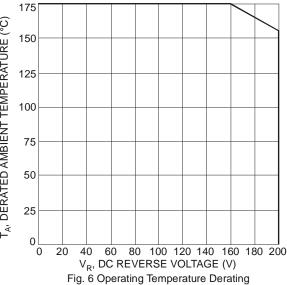


# SBR1U200P1









NEW PRODUCT

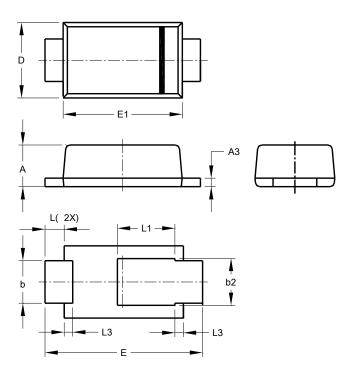
SBR1U200P1 Document number: DS32093 Rev. 3 - 2 Downloaded from Arrow.com.



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI123

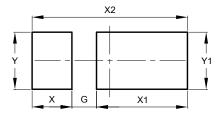


|                      | _     |       |      |  |
|----------------------|-------|-------|------|--|
| PowerDI123           |       |       |      |  |
| Dim                  | Min   | Max   | Тур  |  |
| Α                    | 0.93  | 1.00  | 0.98 |  |
| A3                   | 0.15  | 0.25  | 0.20 |  |
| b                    | 0.85  | 1.25  | 1.00 |  |
| b2                   | 1.025 | 1.125 | 1.10 |  |
| D                    | 1.63  | 1.93  | 1.78 |  |
| Е                    | 3.50  | 3.90  | 3.70 |  |
| E1                   | 2.60  | 3.00  | 2.80 |  |
| L                    | 0.40  | 0.50  | 0.45 |  |
| L1                   | 1.25  | 1.40  | 1.35 |  |
| L3                   | 0.125 | 0.275 | 0.20 |  |
| All Dimensions in mm |       |       |      |  |

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI123



| Dimensions | Value<br>(in mm) |
|------------|------------------|
| G          | 0.65             |
| Х          | 1.05             |
| X1         | 2.40             |
| X2         | 4.10             |
| Y          | 1.50             |
| Y1         | 1.50             |



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